SCBS215B - FEBRUARY 1991 - REVISED JANUARY 1997

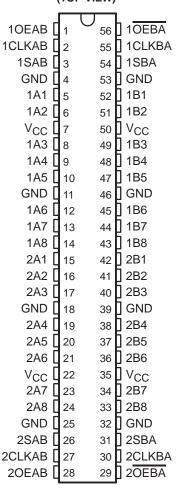
- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OI})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Package and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center **Spacings**

description

The 'ABT16652 are 16-bit bus transceivers that consist of D-type flip-flops and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. These devices can be used as two 8-bit transceivers or one 16-bit transceiver.

Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A low input selects real-time data, and a high input selects stored data. Figure 1 illustrates the four fundamental bus-management functions that performed with the 'ABT16652.

SN54ABT16652...WD PACKAGE SN74ABT16652...DL PACKAGE (TOP VIEW)



Data on the A- or B-data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs regardless of the select- or enable-control inputs. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.



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SCBS215B - FEBRUARY 1991 - REVISED JANUARY 1997

description (continued)

To ensure the high-impedance state during power up or power down, OEBA should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).

The SN54ABT16652 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT16652 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

		INP	UTS			DATA	A 1/0†	ODERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	\uparrow	\uparrow	X	Χ	Input	Input	Store A and B data
Х	Н	1	H or L	Х	Х	Input	Unspecified [‡]	Store A, hold B
Н	Н	1	\uparrow	X‡	Χ	Input	Output	Store A in both registers
L	Х	H or L	\uparrow	Х	Х	Unspecified [‡]	Input	Hold A, store B
L	L	1	\uparrow	Χ	X‡	Output	Input	Store B in both registers
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus

[†] The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



[‡] Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered to load both registers.

SCBS215B - FEBRUARY 1991 - REVISED JANUARY 1997

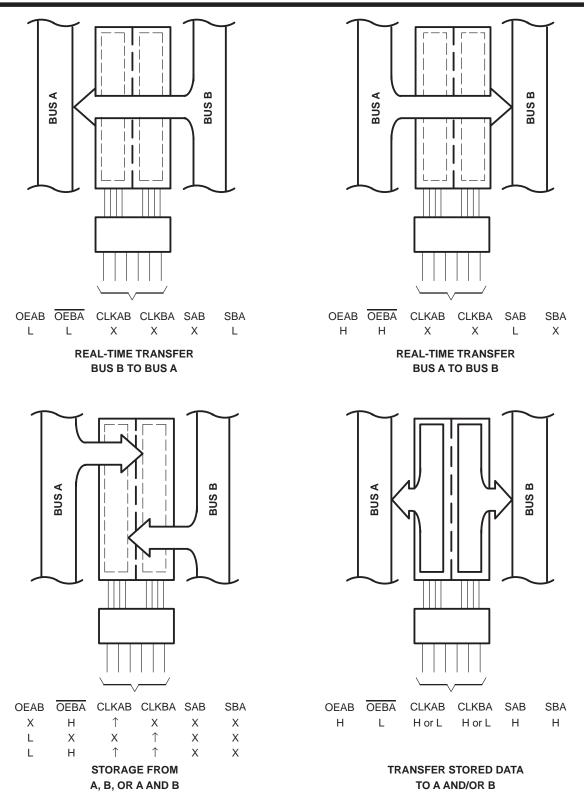
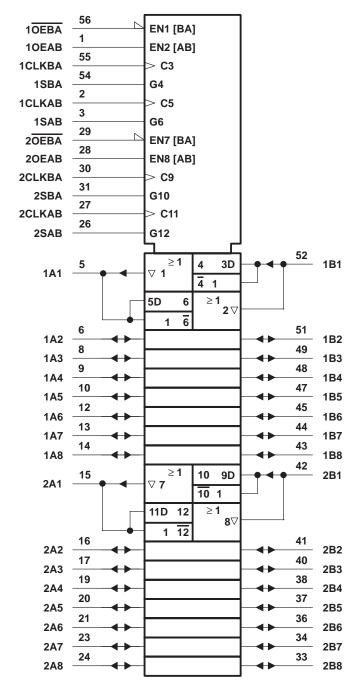


Figure 1. Bus-Management Functions



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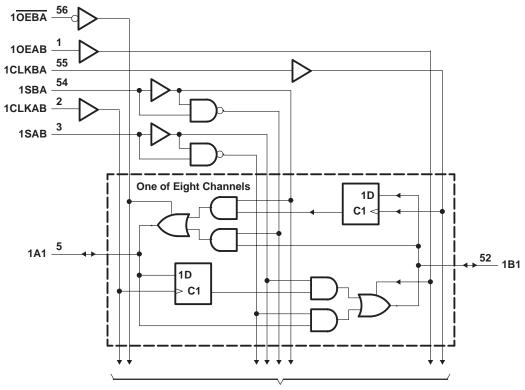
logic symbol†



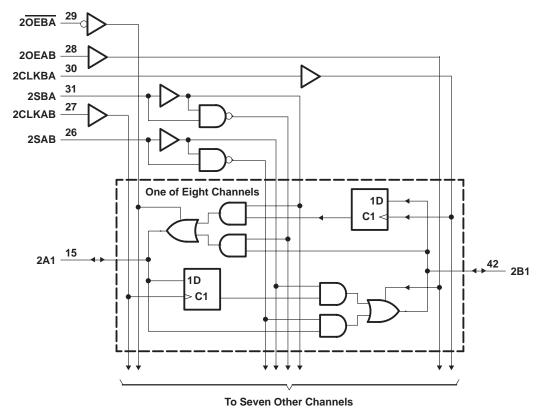
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)









SCBS215B - FEBRUARY 1991 - REVISED JANUARY 1997

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16652	96 mA
SN74ABT16652	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DL package	74°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN54AB1	16652	SN74AB1	16652	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	VCC	V
loh	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		– 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SCBS215B - FEBRUARY 1991 - REVISED JANUARY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAF	RAMETER	TEST CON	DITIONS	T	A = 25°C	;	SN54AB1	Г16652	SN74AB1	16652	UNIT
PAR	KAWETER	TEST CON	DITIONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
٧ıĸ		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
V		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
VOL			I _{OL} = 64 mA			0.55*				0.55	V
V _{hys}					100						mV
II	Control inputs	V _{CC} = 5.5 V, V _I = V ₀	CC or GND			±1		±1		±1	μΑ
	A or B ports					±20		±20		±20	
lozH [‡]		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			10		10		10	μΑ
lozL [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-10		-10		-10	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
ΙΟ§		$V_{CC} = 5.5 \text{ V},$	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		V _{CC} = 5.5 V,	Outputs high			2		2		2	
Icc	A or B ports	$I_{O} = 0$,	Outputs low			32		32		32	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2	
	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			50		50		50	
ΔICC¶	Data inputs	Other inputs at V _{CC} or GND	Outputs disabled			50		50		50	μΑ
	Control inputs	V _{CC} = 5.5 V, One in Other inputs at V _{CC}				50		50		50	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			8						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

SCBS215B - FEBRUARY 1991 - REVISED JANUARY 1997

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		;	SN54AE	T16652		
		V _{CC} =	= 5 V, 25°C	MIN MAX		UNIT
		MIN	MAX			
fclock	Clock frequency	0	125	0	125	MHz
t _W	Pulse duration, CLK high or low	4.3		4.3		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3.5		4		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	0.5		0.5		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			SN74AE	T16652		
		V _{CC} =	= 5 V, 25°C	MIN MAX		UNIT
		MIN MAX				
fclock	Clock frequency	0	125	0	125	MHz
t _W	Pulse duration, CLK high or low	4.3		4.3		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3		ns
th	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0		ns



switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 2)

				SN5	4ABT16	652		
PARAMETER	FROM (INPUT)	TO (OUTPUT)		CC = 5 V 4 = 25°C		MIN	MAX	UNIT
			MIN	TYP	MAX			
f _{max}			125			125		MHz
t _{PLH}	CLK	B or A	1.5	3.1	4	1	5	ns
t _{PHL}	OLIX	BUIA	1.5	3.2	4.1	1	5	115
t _{PLH}	A or B	B or A	1	2.3	3.2	0.6	4	ns
t _{PHL}	AOIB	BULK	1	3	4.1	0.6	4.9	115
t _{PLH}	CAD or CDA†	B or A	1	2.9	4.3	0.6	5.3	ns
t _{PHL}	SAB or SBA†	BULK	1	3.1	4.6	0.6	5.3	115
^t PZH	OEBA	А	1	2.8	4.1	0.6	5.2	ns
t _{PZL}	OEBA	A	1.5	3.1	4.4	1	5.4	115
t _{PHZ}	OEBA	А	1.5	3.4	4.7	0.8	5.3	ns
t _{PLZ}	OEBA	A	1.5	2.7	4	1	5.3	115
^t PZH	OEAB	В	1	2.6	3.6	0.8	4.7	ns
t _{PZL}	UEAD	ь	1.5	2.8	4.5	1	5	115
^t PHZ	OEAB	В	2	4.2	5.9	1	6.4	nc
^t PLZ	OEAB		1.5	3.4	4.9	1	5.9	ns

[†]These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

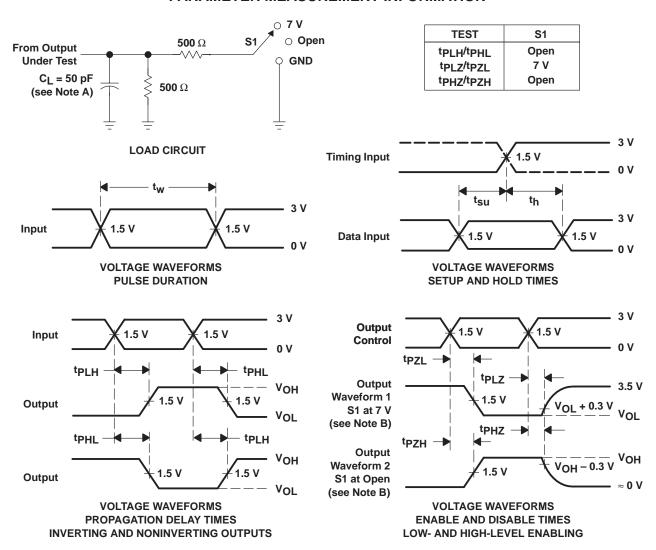
				SN7	4ABT16	652		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, ;	MIN	MAX	UNIT
			MIN	TYP	MAX			
f _{max}			125			125		MHz
t _{PLH}	CLK	B or A	1.5	3.1	4	1.5	4.9	ns
t _{PHL}	CLK	BULA	1.5	3.2	4.1	1.5	4.7	115
^t PLH	A or B	B or A	1	2.3	3.2	1	3.9	ns
t _{PHL}	AOIB	BOIA	1	3	4.1	1	4.6	115
^t PLH	SAB or SBA†	B or A	1	2.9	4.3	1	5	ns
^t PHL	SAB OF SBAT	BOIA	1	3.1	4.3	1	5	115
^t PZH	OEBA	А	1	2.8	4.1	1	5	ns
^t PZL	OEBA	^	1.5	3.1	4.4	1.5	5.3	ns
^t PHZ	OEBA	А	1.5	3.4	4.4	1.5	4.9	ns
t _{PLZ}	OEBA	^	1.5	2.7	3.6	1.5	4	115
^t PZH	OEAB	В	1	2.6	3.6	1	4.2	ns
^t PZL	UEAB	В	1.5	2.8	3.9	1.5	4.6	115
^t PHZ	OEAB	В	2	4.2	5.5	2	5.9	ne
t _{PLZ}	UEAB		1.5	3.4	4.5	1.5	5.2	ns

[†]These parameters are measured with the internal output state of the storage register opposite that of the bus input.



SCBS215B - FEBRUARY 1991 - REVISED JANUARY 1997

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Q} = 50 Ω , t_{f} \leq 2.5 ns, t_{f} \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9584101QXA	ACTIVE	CFP	WD	56	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ABT16652DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16652DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16652DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16652DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABT16652WD	ACTIVE	CFP	WD	56	1	TBD	A42 SNPB	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16652DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16652DLR	SSOP	DL	56	1000	346.0	346.0	49.0

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

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